



CERAMIC

Bandpass Filter

BFHK-7851+

50Ω 6.7 to 8.6 GHz

THE BIG DEAL

- Ultra-High Stopband Rejection Structure – 80 dB typical
- Surface mountable pick and place standard case style
- Standard small 1812 (4.5mm x 3.2mm) case style
- High quality distributed filter topology
- Wide rejection band
- Shielded construction preventing filter from de-tuning
- Reduced footprint area by employing LGA (land grid array)
- Suited for very high-volume production
- Protected by US Patents 11,638,370 and 11,744,057



Generic photo used for illustration purposes only

CASE STYLE: NM1812C-3

+RoHS Compliant

The +Suffix identifies RoHS Compliance. See our website for methodologies and qualifications

APPLICATIONS

- Test and Measurement
- Aerospace and Defense Signal Conditioning

PRODUCT OVERVIEW

The BFHK-7851+ LTCC Band Pass Filter achieves a miniature size and high repeatability of performance by utilizing a proprietary LTCC material system and distributed filter topology. The passband loss at 6.7 – 8.6 GHz is as low as 3.2 dB, with typical stopband rejections at 80 dB up to 18.5 GHz. This model handles up to 1W RF input power, and provides a wide operating temperature range from -55 to +125°C. Utilizing a proprietary LTCC material system and a distributed filter topology, this filter is able to achieve repeatable performance on a lot-to-lot basis.

KEY FEATURES

Feature	Advantages
Ultra-High Rejection	Typical stopband rejections at 80 dB up to 18.5 GHz
Cost effective	LTCC is scalable technology that is cost effective due to ease of production in high quantities.
Small size (4.5mm x 3.2mm)	Allows for high layout density of circuit boards, while minimizing effects of parasitics.
Surface Mountable	Suitable for very high volume automated assembly process.

REV. A
ECO-019695
BFHK-7851+
WY/CP/AM
231102





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ELECTRICAL SPECIFICATIONS¹ AT 25°C

Parameter	F#	Frequency (GHz)	Min.	Typ.	Max.	Units
Center Frequency	—	—	—	7.6	—	GHz
Pass Band	Insertion Loss	F1-F2	—	3.2	4.2	dB
	Return Loss	F1-F2	—	13.0	—	dB
Stop Band, Lower	Insertion Loss	DC-F3	70	80	—	dB
Stop Band, Upper	Insertion Loss	F4-F5	70	80	—	dB

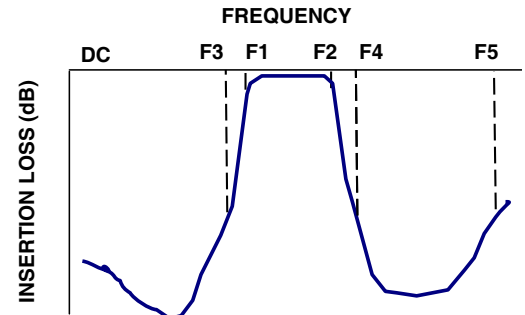
1. Measured on Mini-Circuits Test Board TB-BFHK-7851C+ with feedline losses removed by normalization of S12 and S21 traces to measurements of TB thru-line

MAXIMUM RATINGS

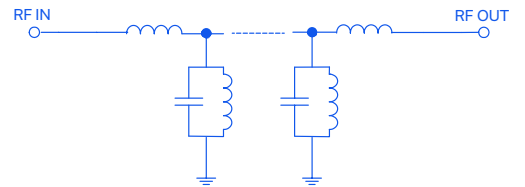
Parameter	Ratings
Operating Temperature	-55°C to 125°C
Storage Temperature	-55°C to 125°C
RF Power Input	1W max.

Permanent damage may occur if any of these limits are exceeded

TYPICAL FREQUENCY RESPONSE



FUNCTIONAL SCHEMATIC



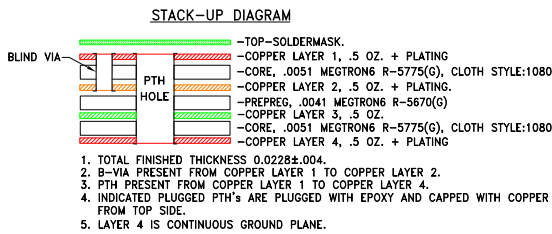
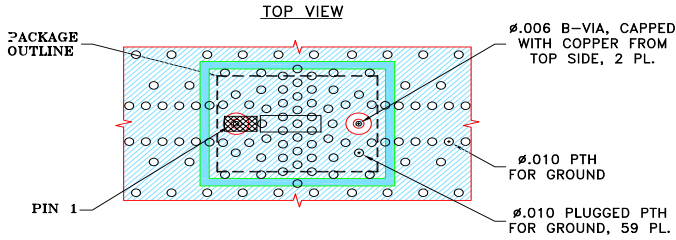


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EVALUATION BOARD MCL P/N: TB-BFHK-7851C+ SUGGESTED PCB LAYOUT: PL-730

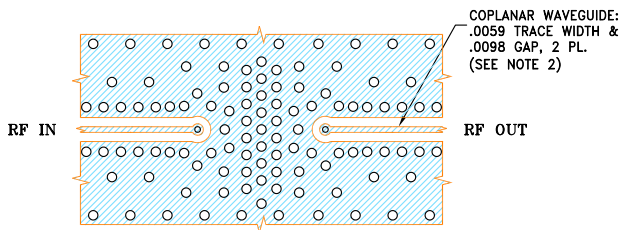


NOTES:

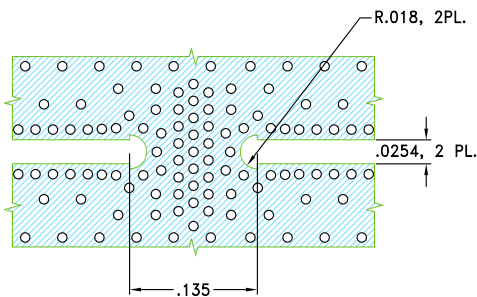
1. PCB IS MULTILAYER PCB, SEE STACK-UP DIAGRAM.
2. TRACE WIDTH & GAP PARAMETERS ARE SHOWN FOR MEGTRON6 R-5775(G), CLOTH STYLE:1080 WITH DIELECTRIC THICKNESS .0051; COPPER: 1/2 OZ.+PLATING. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.
3. COPPER LAYER 4 OF THE PCB ARE CONTINUOUS GROUND PLANE.

- DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER)
- DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

LAYER 2, B-VIA & PTH



LAYER 3 & PTH

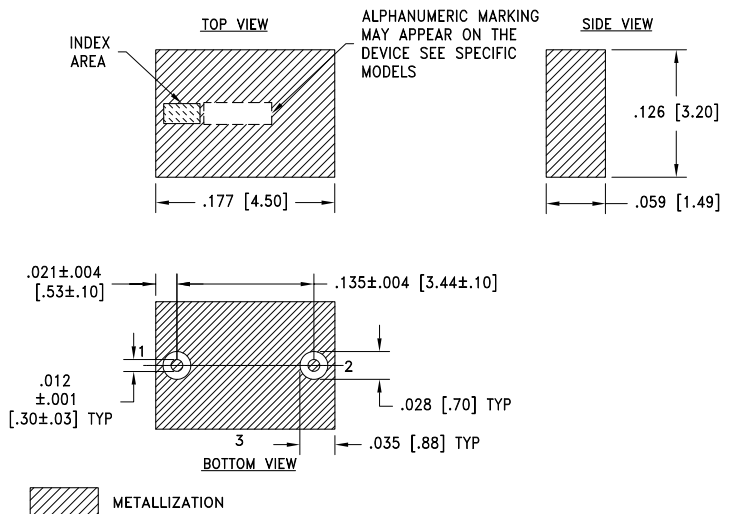


PAD CONNECTIONS

INPUT	1
OUTPUT	2
GROUND	3

PRODUCT MARKING: F477

OUTLINE DRAWING



Weight: .126 grams.

Dimensions are in inches [mm]. Tolerances: 2Pl.±.01; 3Pl. ±.005



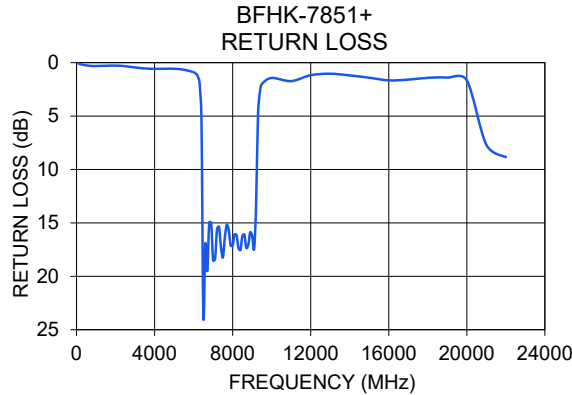
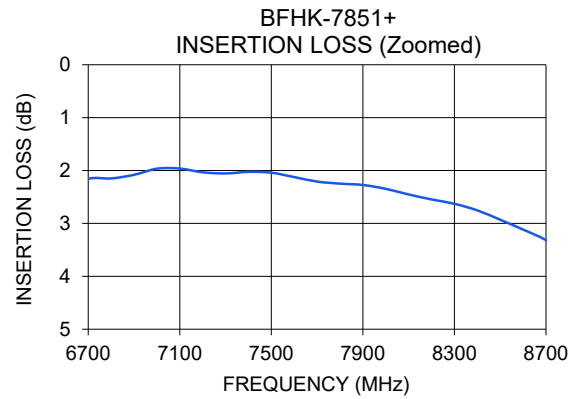
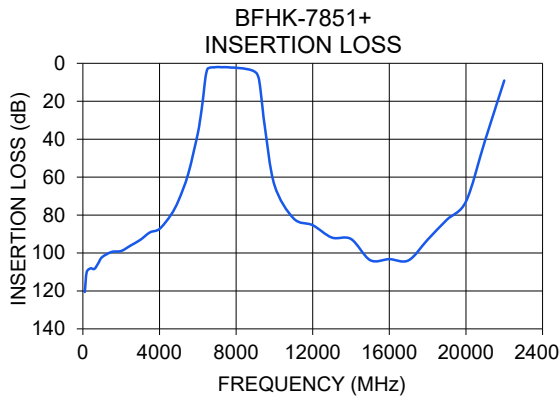
CERAMIC

Bandpass Filter

BFHK-7851+

TYPICAL PERFORMANCE DATA

Frequency (MHz)	Insertion Loss (dB)	Return Loss (dB)
100	120.55	0.08
4600	79.86	0.57
6700	2.16	19.51
7600	2.21	16.35
8600	3.12	16.09
11000	81.76	1.73
12000	85.36	1.17
13000	91.87	1.04
14000	92.62	1.19
15000	103.78	1.41
16000	103.25	1.66
17000	103.89	1.59
18000	92.98	1.42
19000	82.49	1.40
20000	72.89	1.66
21000	40.62	7.68
22000	9.09	8.84



- NOTES**
- A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
 - B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.
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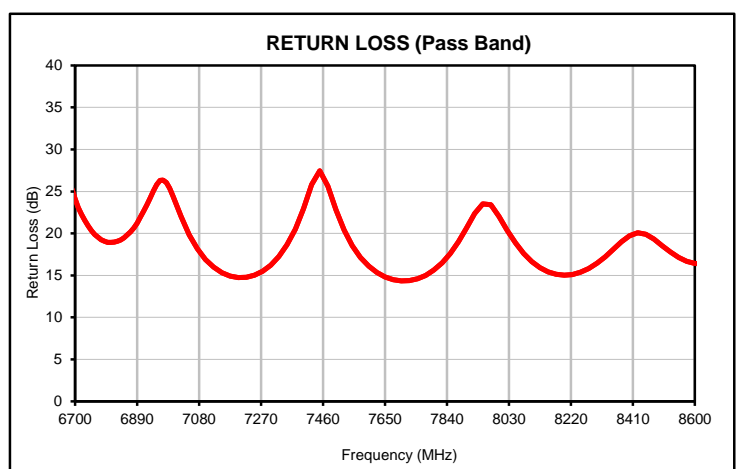
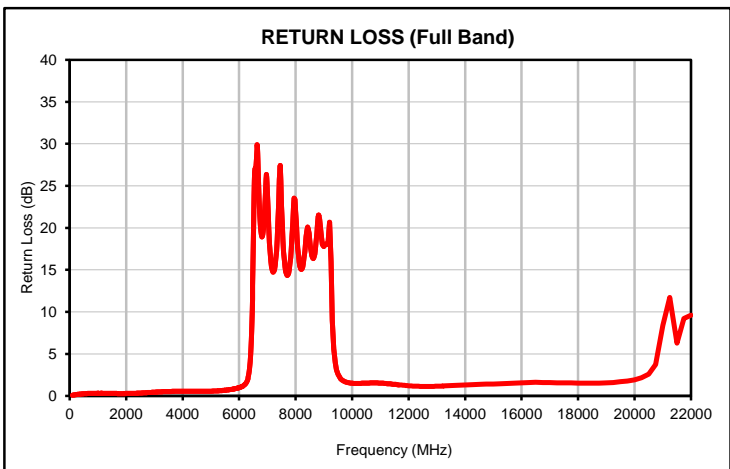
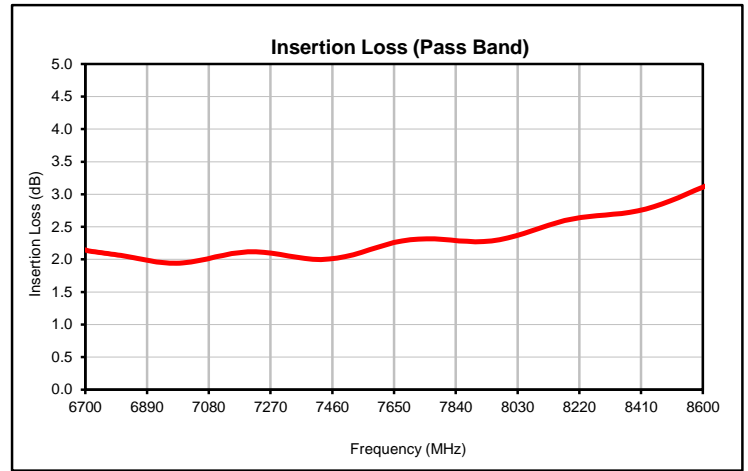
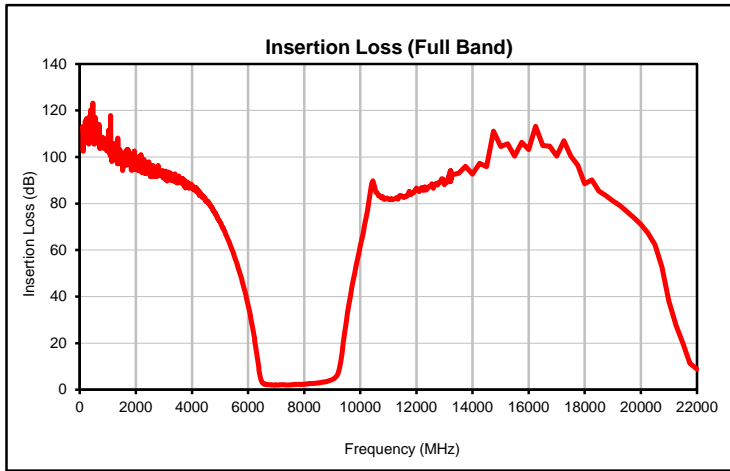
Ceramic Bandpass Filter

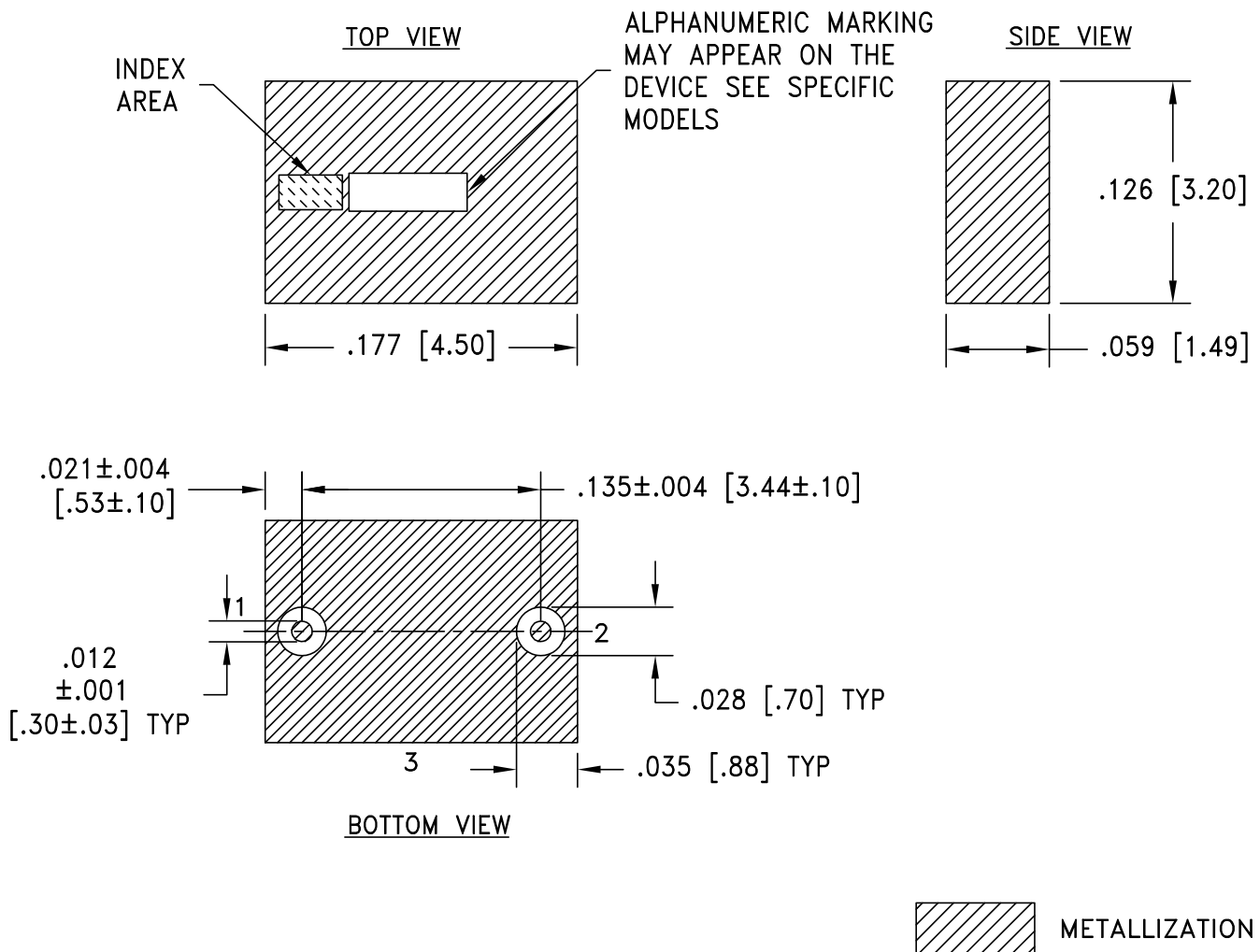
BFHK-7851+

Typical Performance Data

FREQUENCY (MHz)	INSERTION LOSS (dB)	RETURN LOSS (dB)
100	120.55	0.08
200	110.05	0.15
400	108.10	0.23
600	108.40	0.28
800	105.47	0.31
1000	102.23	0.31
1500	99.45	0.29
2000	98.95	0.27
2500	96.02	0.33
3000	93.05	0.45
3500	89.14	0.54
4000	87.31	0.58
4600	79.86	0.57
5000	72.17	0.57
5500	58.30	0.66
6000	36.99	0.90
6100	31.15	1.01
6200	24.36	1.23
6300	16.32	1.84
6400	7.46	5.04
6500	3.04	23.78
6600	2.42	16.97
6700	2.16	19.51
6800	2.15	14.96
6900	2.08	15.00
7000	1.97	18.51
7100	1.96	18.39
7200	2.03	15.60
7300	2.05	15.35
7400	2.03	17.24
7500	2.04	18.24
7600	2.12	16.35
7700	2.21	15.17
7800	2.25	15.69
7900	2.27	17.11
8000	2.35	17.11
8100	2.45	16.09
8200	2.55	16.15
8300	2.63	17.37
8400	2.75	17.53
8500	2.93	16.21
8600	3.12	16.09
8700	3.32	17.34
8800	3.61	17.08
8900	4.03	15.89
9000	4.62	16.20
9100	5.71	17.44
9200	8.73	13.45
9300	16.35	4.81
9400	25.34	2.71
9500	33.43	2.00
10000	64.14	1.43
11000	81.76	1.73
12000	85.36	1.17
13000	91.87	1.04
14000	92.62	1.19
15000	103.78	1.41
16000	103.25	1.66
17000	103.89	1.59
18000	92.98	1.42
19000	82.49	1.40
20000	72.89	1.66
21000	40.62	7.68
22000	9.09	8.84

Typical Performance Curves





Weight: .126 grams.

Dimensions are in inches [mm]. Tolerances: 2 Pl.±.01; 3 Pl. ±.005 Inches

Notes:

1. Case material: Ceramic.
2. Termination Finish: **as shown below or indicated on Data Sheet.**
For RoHS Case Styles: Tin Plate over Nickel plate. All models, (+) suffix.

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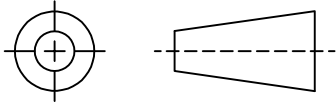
P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For detailed performance specs & shopping online see Mini-Circuits web site



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RF/IF MICROWAVE COMPONENTS

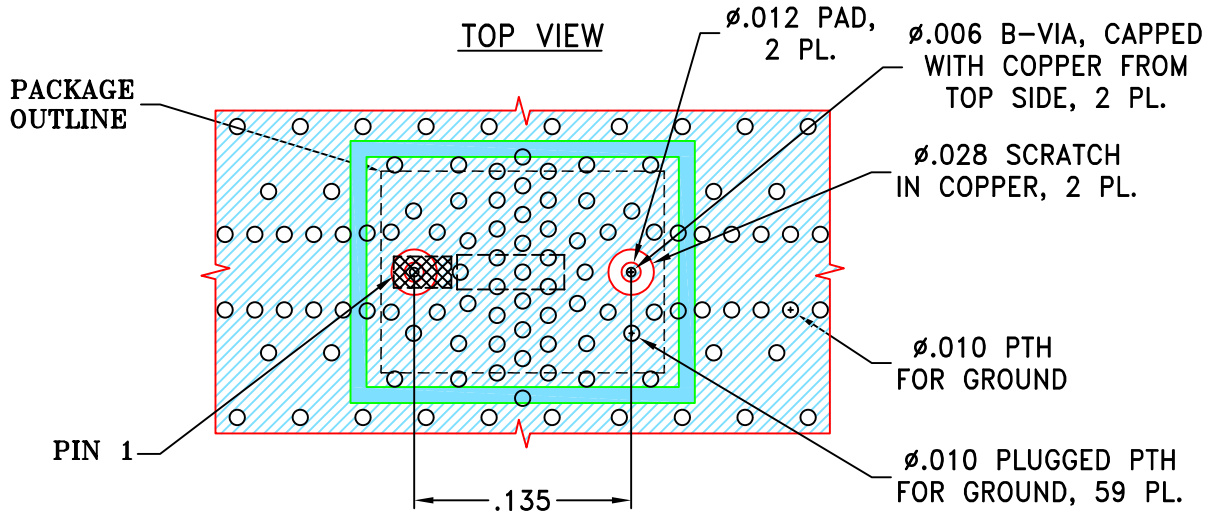
THIRD ANGLE PROJECTION



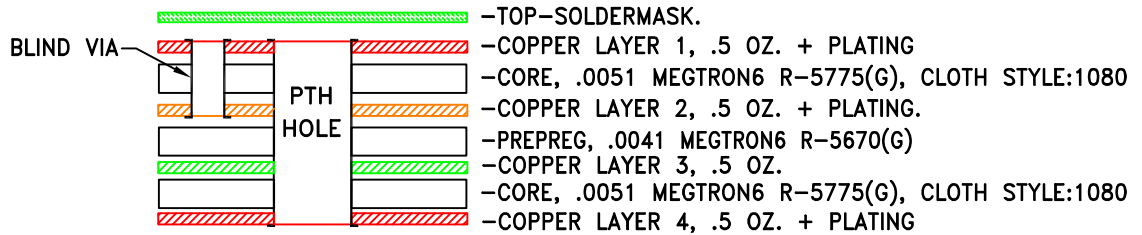
REVISIONS

REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
OR	ECO-013254	NEW RELEASE	05/16/22	ITG	IL
A	ECO-015587	UPDATED STACK-UP DIAGRAM	11/01/22	ITG	IL
B	ECO-020890	ADDED DIMENSIONS	02/16/24	ITG	IL

SUGGESTED MOUNTING CONFIGURATION FOR
NM1812C-3 CASE STYLE



STACK-UP DIAGRAM



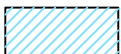
- TOTAL FINISHED THICKNESS 0.0228±.004.
- B-VIA PRESENT FROM COPPER LAYER 1 TO COPPER LAYER 2.
- PTH PRESENT FROM COPPER LAYER 1 TO COPPER LAYER 4.
- INDICATED PLUGGED PTH'S ARE PLUGGED WITH EPOXY AND CAPPED WITH COPPER FROM TOP SIDE.
- LAYER 4 IS CONTINUOUS GROUND PLANE.

NOTES:

- PCB IS MULTILAYER PCB, SEE STACK-UP DIAGRAM.
- TRACE WIDTH & GAP PARAMETERS ARE SHOWN FOR MEGTRON6 R-5775(G), CLOTH STYLE:1080 WITH DIELECTRIC THICKNESS .0051; COPPER: 1/2 OZ.+PLATING. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.
- COPPER LAYER 4 OF THE PCB ARE CONTINUOUS GROUND PLANE.



DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER)



DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

UNLESS OTHERWISE SPECIFIED	INITIALS		DATE
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS ± 3 PL DECIMALS ± .005 ANGLES ± FRACTIONS ±	DRAWN	ITG	05/16/22
	CHECKED	GF	05/16/22
	APPROVED	IL	05/16/22



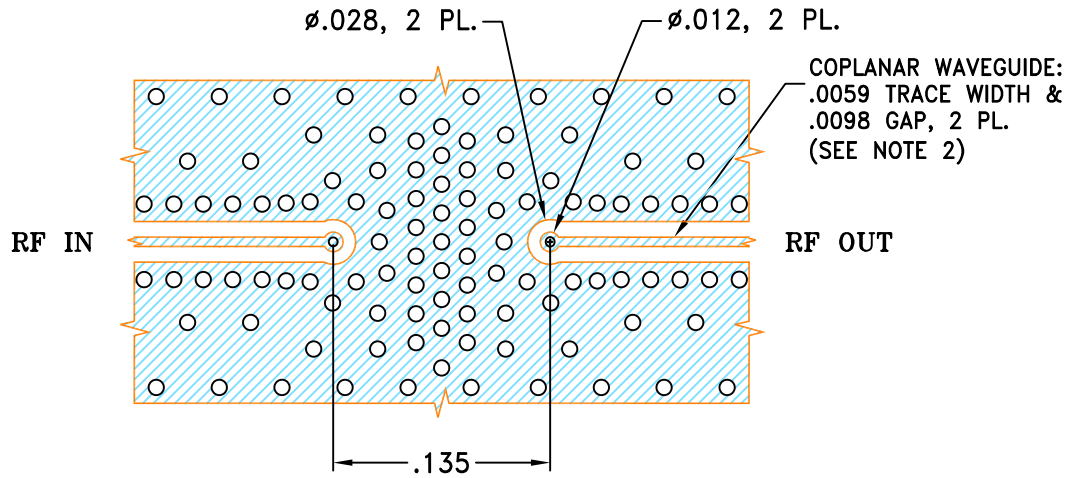
Mini-Circuits[®] 13 Neptune Avenue
Brooklyn NY 11235

PL, NM1812C-3, TB-1239

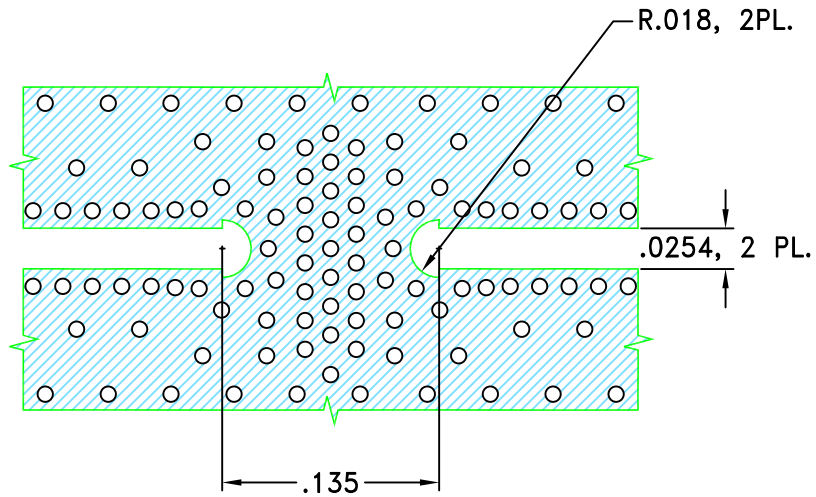
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SIZE	CODE IDENT	DRAWING NO:	REV:
A	15542	98-PL-730	B
FILE:	98PL730	SCALE: 8:1	SHEET: 1 OF 2

LAYER 2, B-VIA & PTH



LAYER 3 & PTH



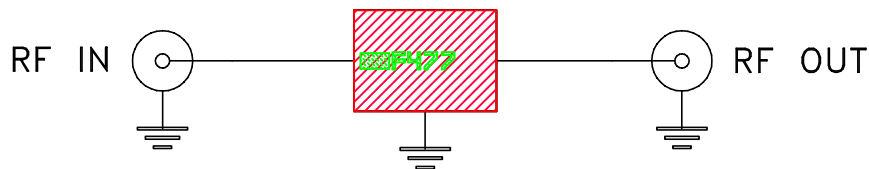
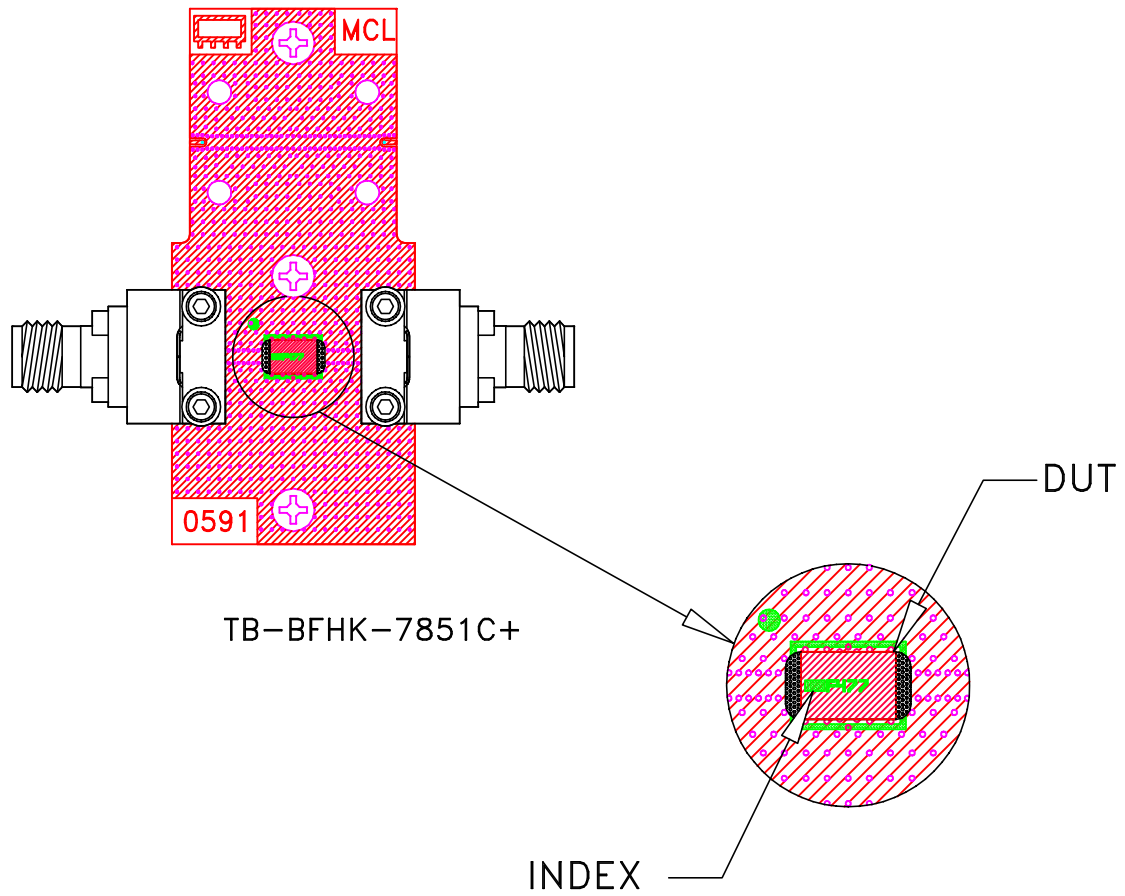
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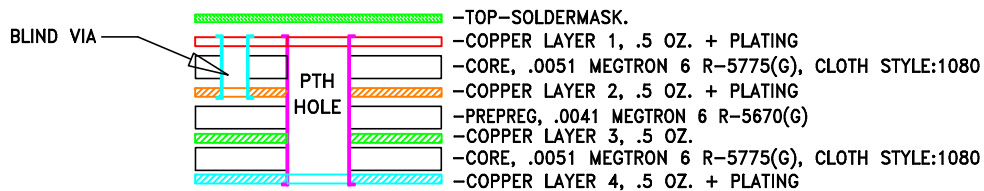
ALL DIMENSIONS ARE IN INCHES EXCEPT OTHERWISE SPECIFIED

SIZE A	CODE IDENT 15542	DRAWING NO: 98-PL-730	REV: B
FILE: 98PL730	SCALE: 8:1	SHEET: 2 OF 2	

Evaluation Board and Circuit




Schematic Diagram



STACK-UP DIAGRAM

Notes:

1. 2.92 mm Female End Launch Connector.
2. PCB Material: Megtron 6 R5775(N).
Dielectric Constant=3.6.
3. Total finished thickness .023".

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All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Thermal Cycling	-55 to 125°C, 100 cycles, Dwell Time 15 minutes.	MIL-STD-202, Method 107, Condition A-3
Mechanical Shock	50g, 11ms half-sine, 18 shocks applied each to 3 axes	MIL-STD-202 Method 213, Condition A
Vibration	10-2000Hz sine, 20g, 12 cycles applied each to 3 axes	MIL-STD-202, Method 204, Condition D
Constant Acceleration	30Kg, Y1 Direction	MIL-STD-883, Method 2001, Condition E
Humidity	85°C, 90-95% Relative Humidity, 250hours	
Solderability	10X / 30X Magnification	J-STD-002C Test S, J-STD-002C Test S1
High Temp Storage	125°C, 250 hours	